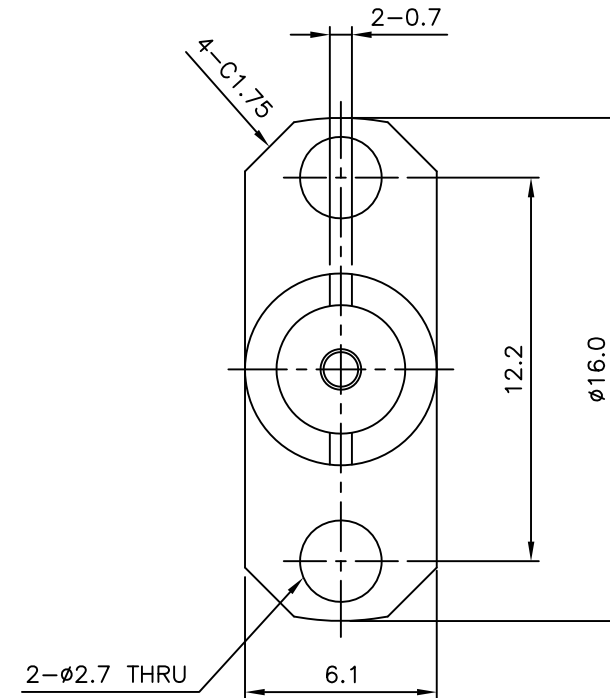
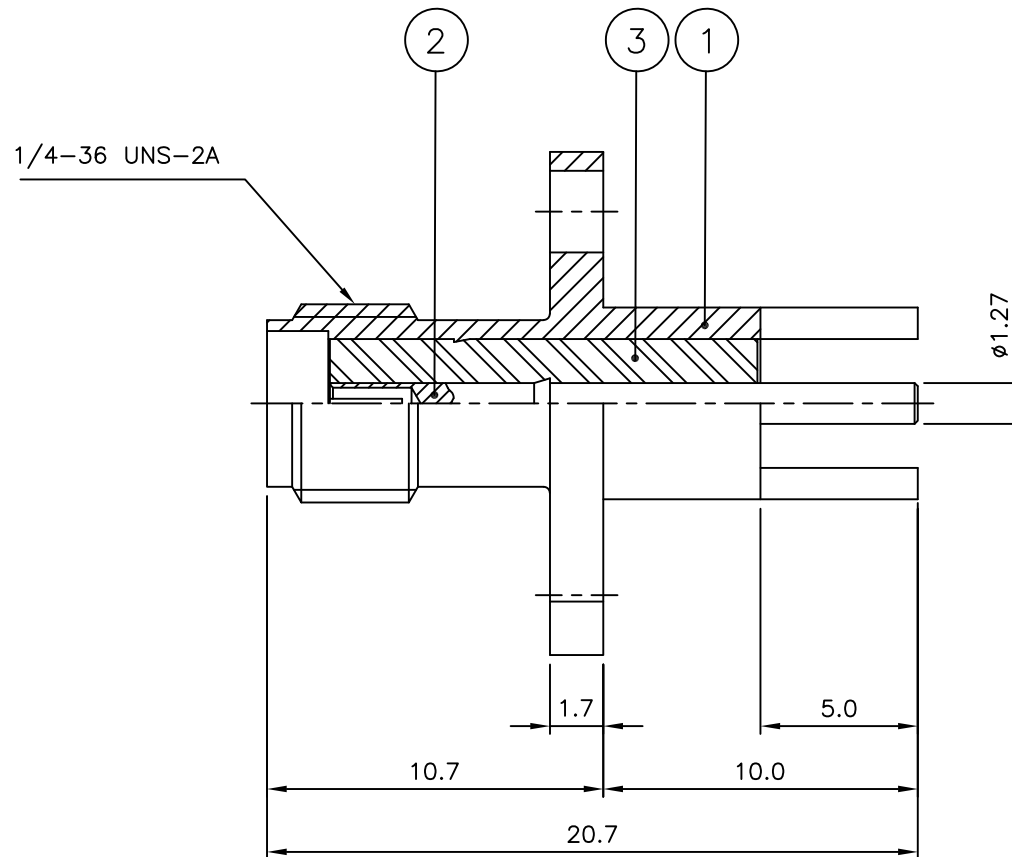


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1R	Initial Registration	I.C.KIM	I.C.KIM	2013.04.10.
1	조립성 개선을 위한 닙시바늘 위치 변경	G.Y.KIM	I.C.KIM	2016.11.11.
2	[설번No.202212-0006] 절연체 돌출 방지로 인한 부품코드 변경	S.Y.EUN	S.H.KIM	2022.12.26.



2	3	INSULATOR	1	TEFLON		DIN03334-N/1 DIN02162-N/1
	1	2	CONTACT	1	BeCu	Gold Plate
1	1	BODY	1	MBsBD	Gold Plate	DBD03308-5/1
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2022. 12. 26.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY S.H.KIM	CHECKED BY	
MATERIAL -		DRAWN BY S.Y.EUN	TITLE SMA50 SOLDER END JS-2H-2R	
FINISH -	SCALE 4/1	UNIT mm		DWG NO. CN02976-7/1 REVISION 2 SHEET 1 of 1